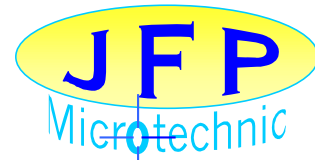


# JFP Model PP6-6



## Manual & Semi Automatic Universal Flip Chip Die-Bonder



The Flip Chip Die Bonder model PP6-6 is designed for accurate placement of delicate devices on substrate.

It achieves high accuracy placement using high magnification optical device. The machine provides for single collet vacuum pick and place of die from waffle pack, wafer, Gel-Pak or bulk die media and features adjustable and repeatable subsonic scrub. The placement accuracy is  $< 3\mu\text{m}$ , upon configuration.

Small and large devices can be placed with flipped vision.

All process options of PP6 series are available on PP6-6.

A full automated die bonding sequence with according epoxy pattern are programmable Off-Line... as a simple matrix or multiple locations..

A robust, and reliable mechanical concept, designed to be external vibration free.

Easy to use, flexible, the PP6-6 requires only minimum training to operate

### DIE & SUBSTRATE

- Minimum die size 150\*150 $\mu\text{m}$
- Maximum die size 40\*40 mm (more in option)
- Substrate handling, Up to 200x300 mm.

### VISION SYSTEM

- Optical Zoom 10X, Magnification up to 180X
- CCD Color camera high resolution
- TFT monitor 17"
- Lighting
- Direct placement
- 2 reference points for auto-centering placement
- Indexed Pick& Place Positioning

### XY TABLE

- Motorized X 260mm, Y 120mm,  $x1\mu\text{m}$
- Vibration free
- Motion control with progressive joystick

### PARAMETERS & DISPLAY

- PC Interface, GUI Menu
- Programmable force 10gr to 700 gr
- Opt: 5 kg
- Programmable bond time
- Programmable scrub
- Indexed Pick and Placement mode
- Vacuum selectable
- Flip Chip, small & large dies
- Eutectic Chuck,+ gas environment
- Programmable ramp-up Temperature

### NEW AUTOMATIC MODE

### NEW Laser Reflow Option

### OPTIONS

- Dispenser
- Stamping
- UV
- Ultrasonic
- Sorter: Eject system for wafer
- Customized work holder
- Hot gaz gun
- OFF LINE PROGRAMMING
- MULTI-SEQUENCES
- REWORK PROCESS + SHEAR KIT

### TECHNICAL SPECIFICATION

Power:	230VAC 500watt,
Vacuum:	70%
Dimensions:	650*820*1450mm
Weight:	90kg.
Compressed Air	6 bar

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